



# RF3100-3K

## Absolute Maximum Ratings

Parameter	Rating	Unit
Supply Voltage (RF off)	+8.0	V <sub>DC</sub>
Supply Voltage (P <sub>OUT</sub> ≤ 29dBm)	+5.2	V <sub>DC</sub>
Control Voltage (V <sub>REG</sub> )	+4.2	V <sub>DC</sub>
Mode Voltage (V <sub>MODE</sub> )	+3.5	V <sub>DC</sub>
Input RF Power	+10	dBm
Operating Case Temperature	-30 to +110	°C
Storage Temperature	-30 to +150	°C



**Caution!** ESD sensitive device.

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Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
<b>High Power State</b> (V <sub>MODE</sub> Low)					Typical Performance at V <sub>CC</sub> =3.2V, V <sub>REG</sub> =2.85V, T <sub>AMB</sub> =25°C, Frequency=1750MHz to 1780MHz (unless otherwise specified)
Frequency Range	1750		1780	MHz	
Linear Gain	25.5	27.5		dB	
Second Harmonic		-49		dBc	
Third Harmonic		-52		dBc	
Maximum Linear Output Power (CDMA Modulation)	28			dBm	
Total Linear Efficiency		35		%	P <sub>OUT</sub> =28dBm
Adjacent Channel Power Rejection		-46	-44.5	dBc	ACPR @ 1.25MHz, P <sub>OUT</sub> =28dBm
		-60	-57.5	dBc	ACPR @ 2.25MHz, P <sub>OUT</sub> =28dBm
Input VSWR		<2:1			
Output VSWR			10:1 6:1		No damage. No oscillations. >-70dBc
Noise Power		-141		dBm/Hz	At 90MHz offset.
<b>Low Power State</b> (V <sub>MODE</sub> High)					Typical Performance at V <sub>CC</sub> =3.2V, V <sub>REG</sub> =2.85V, T <sub>AMB</sub> =25°C, Frequency=1750MHz to 1780MHz (unless otherwise specified)
Frequency Range	1750		1780	MHz	
Linear Gain	17	20		dB	
Second Harmonic		-49		dBc	
Third Harmonic		-52		dBc	
Maximum Linear Output Power (CDMA Modulation)	16			dBm	
Adjacent Channel Power Rejection		-52	-46.5	dBc	ACPR @ 1.25MHz
		-66	-61	dBc	ACPR @ 2.25MHz
Input VSWR		<2:1			
Output VSWR			10:1 6:1		No damage. No oscillations. >-70dBc

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Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
<b>DC Supply</b>					$T_{AMB}=25^{\circ}C$
Supply Voltage	3.2	3.7	4.2	V	
Quiescent Current		170	240	mA	$V_{MODE}=Low, V_{REG}=2.85V$
		50	80	mA	$V_{MODE}=High, V_{REG}=2.85V$
$V_{REG}$ Current		6	10	mA	
$V_{MODE}$ Current			1.5	mA	
Turn On/Off Time			6	$\mu s$	
Total Current (Power Down)		5	10	$\mu A$	$V_{REG}=Low, V_{MODE}=Low$
$V_{REG}$ "Low" Voltage	0		0.5	V	
$V_{REG}$ "High" Voltage	2.8	2.85	2.9	V	
$V_{MODE}$ "Low" Voltage	0		0.5	V	
$V_{MODE}$ "High" Voltage	2.0		3.0	V	

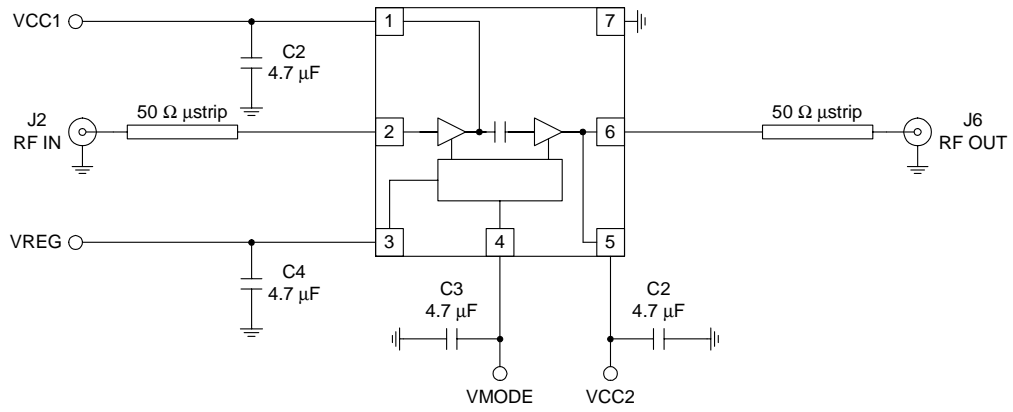
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POWER AMPLIFIERS

Pin	Function	Description	Interface Schematic
1	VCC1	First stage collector supply. A low frequency decoupling capacitor (e.g., 1 $\mu$ F) is required.	
2	RF IN	RF input internally matched to 50 $\Omega$ . This input is internally AC-coupled.	
3	VREG	Regulated voltage supply for amplifier bias. In Power Down mode, both V <sub>REG</sub> and V <sub>MODE</sub> need to be LOW (<0.5V).	
4	VMODE	For nominal operation (High Power Mode), V <sub>MODE</sub> is set LOW. When set HIGH, devices are turned off to improve efficiency.	
5	VCC2	Output stage collector supply. A low frequency decoupling capacitor (e.g., 1 $\mu$ F) is required.	
6	RF OUT	RF output internally matched to 50 $\Omega$ . This output is internally AC-coupled.	
7	GND	Ground connection. Connect to package base ground. For best performance, keep traces physically short and connect immediately to ground plane.	
Pkg Base	GND	Ground connection. The backside of the package should be soldered to a top side ground pad which is connected to the ground plane with multiple vias. The pad should have a short thermal path to the ground plane.	

## Evaluation Board Schematic (Download [Bill of Materials](http://www.rfmd.com) from [www.rfmd.com](http://www.rfmd.com).)



# RF3100-3K

## Evaluation Board Layout Board Size 1.5" x 1.5"

Board Thickness 0.032", Board Material FR-4, Multi-Layer, Ground Plane at 0.014"

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POWER AMPLIFIERS

